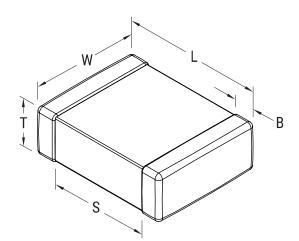


CKC33C104GWGACTU

Aliases (CKC33C104GWGAC7800) KC-LINK Comm COG, Ceramic, 0.1 uF, 2%, 650 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 3640, 6.3 mm



Click here for the 3D model.

General Information	
Series	KC-LINK Comm COG
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	790 mg
Shelf Life	78 Weeks
MSL	1

		Specifications
	3640	Capacitance
	9.3mm +/-0.6mm	Measurement Condition
	10.2mm +/-0.4mm	Tolerance
	2mm +/-0.20mm	Voltage DC
	6.3mm MIN	Dielectric Withstanding Voltage
	1.27mm +/-0.4mm	Temperature Range
		Temp. Coefficient
ifications		Capacitance Change with
	T&P 180mm Plastic Tane	Reference to +25°C and 0 VDC

т	2mm +/-0.20mm
S	6.3mm MIN
В	1.27mm +/-0.4mm
Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	250

Specifications	
Capacitance	0.1 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	2%
Voltage DC	650 VDC
Dielectric Withstanding Voltage	845 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Dimensions Chip Size

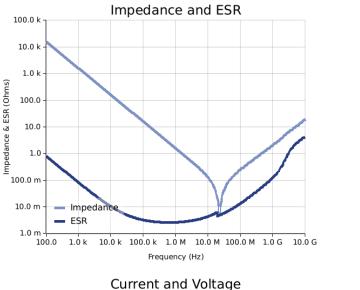
L W

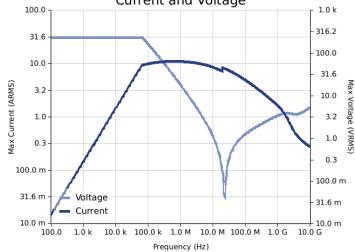


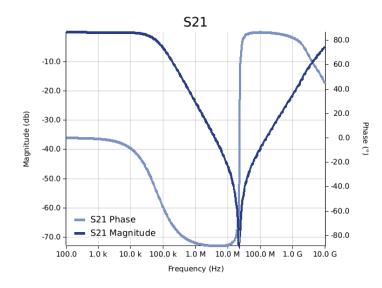
CKC33C104GWGACTU Aliases (CKC33C104GWGAC7800) KC-LINK Comm C0G, Ceramic, 0.1 uF, 2%, 650 VDC, C0G, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 3640, 6.3 mm

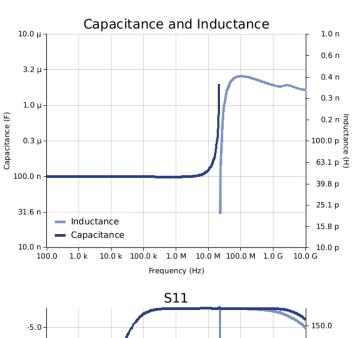
Simulations

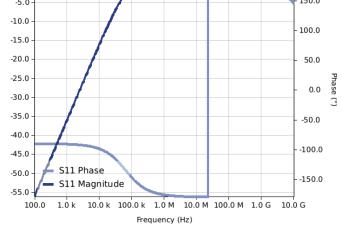
For the complete simulation environment please visit K-SIM.











Magnitude (db)

Generated 06/28/2025



CKC33C104GWGACTU

Aliases (CKC33C104GWGAC7800) KC-LINK Comm COG, Ceramic, 0.1 uF, 2%, 650 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 3640, 6.3 mm

These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for hipple klipple current younge vs. requericy plots is the ESR at an bient temperature.
 The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The effects shown herein are based on measured data from a multiple part sample of the parts in question.
 Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages are applied to reach previous the burger of the parts.
- generated at any other harmonics. Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.